



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE94108EL	Issued	03. June 2021
MA#	MA005429544		
Package	PG-SSOP-24-9	Weight*	150.84 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.240	2.15	2.15	21480	21480
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8918	
	non noble metal	copper	7440-50-8	54.617	36.21	37.15	362094	371569
wire	non noble metal	copper	7440-50-8	0.850	0.56	0.56	5632	5632
encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1148	
	plastics	epoxy resin	-	7.965	5.28		52808	
	inorganic material	silicondioxide	60676-86-0	78.441	52.01	57.40	520038	573994
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19299	19299
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.244	0.16		1618	
	noble metal	silver	7440-22-4	0.732	0.49	0.65	4855	6473
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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